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5962-E1267

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE $1.1\,$ Scope. This drawing describes device requirements for class B microcircuits in accordance with $1.\overline{2.1}$ of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". 1.2 Part number. The complete part number shall be as shown in the following example: 5962-87701 Device Case outline Lead finish per Drawing number (1.2.2)MIL-M-38510 1.2.1 Device types. The device types shall identify the circuit function as follows: Circuit function Device type Generic number 7528 CMOS dual 8-bit buffered DAC, ±4 LSB's of gain error 01 CMOS dual 8-bit buffered DAC, ±2 LSB's of gain error CMOS dual 8-bit buffered DAC, ±1 LSB's of gain error 7528 02 03 7528 1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows: Case outline Outline letter D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package 2 1.3 Absolute maximum ratings. Supply voltage - - - - - - - - - - - - - - - - -+5 V dc to +15 V dc V_{DD} to AGND - - - - - - - - - - - - - - - - - V_{DD} to DGND - - - - - - - - - - Digital input voltage to DGND - - - - - - - - - - -0 V dc, +17 V dc 0 V dc, +17 V dc -0.3 V dc to +15 V dc ±25 V dc **±25 V dc** -0.3 V dc to VDD -0.3 V dc to +15 V dc V pin 2, V pin 20 to AGND ------AGND to DGND - - - - - - - - - - - - - - - - $-0.3 \text{ V}, \text{ V}_{DD} + 0.3 \text{ V}$ DGND to AGND - - - - - - - - - - - - - - - -Power dissipation (P_D) Up to +75°C ----450 mW Derate above +75°C - - - - - - - - - - - -6 mW/°C -65°C to +150°C +300°C Storage temperature range - - - - - - - - - - - -Lead temperature (soldering, 10 seconds) - - - - - -See MIL-M-38510, appendix C +120°C 1.4 Recommended operating conditions. -55°C to +125°C +4.75 V dc to +5.25 V dc and Operating ambient temperature range (T_A) - - - - - -Supply voltage range (VDD) - - - - - - - - - - - -+14.25 V dc to +15.75 V dc +10 Y dc 0 V dc SIZE **STANDARDIZED** Α 5962-87701 MILITARY DRAWING

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.2.2 Functional diagram and mode selection. The functional diagram and mode selection shall be as specified on figure 2.
- 3.2.3 Write cycle timing diagram. The write cycle timing diagram shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full ambient operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

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TABLE I. Electrical performance characteristics. Conditions $\frac{1}{-55}^{\circ}$ C \leq T_A \leq +125 $^{\circ}$ C unless otherwise specified Unit |Device | Group A Limits Symbol 3 Test types subgroups Min Max RES 1,2,3 8 Bits **Resolution** V_{DD} = +5 V A11 8 1,2,3 $V_{DD} = +15 \text{ V}$ **A11** Relative accuracy $\underline{\frac{2}{}}$ $V_{DD} = +5 V$ 01 1,2,3 ±1 LSB ±1 02 1 ±.5 2,3 V_{DD} = +5 V T_A = +25°C **±.**5 12 V_{DD} = +5 V 03 1 ±1 ±.5 2,3 ***.**5 V_{DD} = +5 V T_A = +25°C 12 $V_{DD} = +15 V$ ±1 01 1,2,3 02 ±1 2,3 ±.5 V_{DD} = +15 V T_A = +25 °C ±.5 12 03 ±1 $V_{DD} = +15 \text{ V}$ 1 2,3 ±.5 V_{DD} = +15 V T_A = +25 °C **±.5** 12

See footnotes at end of table.

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 \pm U. 8. GOVERNMENT PRINTING OFFICE: 1988--550-547

Test	Symbol	55.	Conditions	1/	Device	Group A	Limits		 Unit
		unless o	C < T _A < +1: therwise spe	cified	types	subgroups	Min	Max	<u> </u>
Gain error 3/	AE	DAC regis	ter loaded 1111 1111	VDD	01	1 1		±4	LSE
		 Mifu IIII	1111 1111	="+5 V 	! 	2,3		±6	<u> </u>
				<u> </u>	02	1,2,3		±4	<u> </u> -
				V _{DD} = +5 V T _A = +25°C		12		±2	
	İ	İ		1	03	1 1		±4	†
				V _{DD} = +5 V		2,3	±3	T	
		 		V _{DD} = +5 V T _A = +25°C		12 12 		±1 	T
		<u> </u> 		ν _{DD}	01	1 1		±4	
				= +15 V		2,3		 ±5	1
					02	1		±4	
						2,3		±3	
	 	! ! !		V _{DD} = +15 V T _A = +25°C		12		 ±1 	
		 		 V _{DD} = + 15 V	03	1		±4	
		 		= + 15 V 	 	2,3		± 1	
		 		V _{DD}		12		±1	
ifferential nonlinearity	DNL		/, all grade i monotonic iting temper	s to 8-bits	All	1,2,3		±1	LSB
		guaranteed	V, all grad I monotonic iting temper	to 8-bits!	All	1,2,3		± 1	
See footnotes at	end of table	e.					_		
STANDA MILITARY	SIZE A		5962-87701						

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-55°C < TA < + unless otherwise s ΔVDD = ±5% DAC latches loaded with 0000 0000	VDD = +5 V VDD = +5 V VDD = +5 V VDD = +5 V VDD = +5 V VDD = +5 V VDD = +5 V VDD = +15 V VDD =	types	subgroups 1	Min	.02 .04 .01 .02 .2 .20 .20 .20 .20 .20 .20 .20	±%/%
DAC latches loaded	V _{DD}	A11 A11 A11 A11	2,3 1 2,3 1 2,3 1 2,3 1 2,3		.04 .01 .02 ±50 ±400 ±50 ±50	-
	V _{DD}	A11	1 2,3 1 2,3 1 2,3 1 2,3		.01 .02 ±50 ±400 ±50 ±200	- nA
	V _{DD} = +5 V	A11	2,3 1 2,3 1 2,3 1 2,3		±50 ±400 ±50 ±200 ±50	- nA
	V _{DD} = +5 V	A11	1 2,3 1 1 2,3 1 2,3 1 2,3		±50 ±400 ±50 ±200 ±50	
	= +5 V V _{DD} = +15 V V _{DD} = +5 V	A11	2,3		±400	_ nA - - -
With 6500 5555	 V _{DD} = +15 V V _{DD} = +5 V	A11	1 2,3 1 2,3		±50 ±200 ±50	- - -
	 V _{DD} = +5 V	A11	2,3		±200 ±50	- -
	 V _{DD} = +5 V	<u> </u> 	2,3		±50	
	= +5 V 	<u> </u> 	2,3		1	-
	 	 A11	T		±400	
	V _{DD} = +15 V	A11			 i	
	= +15 V		1		±50	-
!		<u>i </u>	2,3		±200	
į	ν _{DD} = +5 γ	 A11 	1,2,3	8	15	kΩ
	ν _{DD} = +15 γ	A11	1,2,3	8	15	
	YDD v	A11	1,2,3	2.4		V
	V _{DD} = +15 V	A11	1,2,3	13.5		-
	ν _{DD} = +5 ν	A11	1,2,3		0.8	-
	V _{DD} = +15 V	A11	1,2,3		1.5	
V _{IN} = 0 V or V _{DD}	V _{DD}	A11	1 1		±1	μА
	1= +5 V	<u> </u>	2,3		±10	
	VDD	A11	1		±1	_
]= +15 Y	<u> </u>	2,3	 	±10	
le.						
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	NG SIZE A	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}

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TABLE I. Electrical performance characteristics - Continued. Conditions $\frac{1}{\text{Conditions}}$ $\frac{1}{\text{Conditions}}$ $\frac{1}{\text{Conditions}}$ $\frac{1}{\text{Conditions}}$ unless otherwise specified Test Symbol Limits Unit |Device | Group A types subgroups Min Max Supply current from \mathbf{V}_{DD} ν_{DD} - +<u>5 ν</u> I DD All digital inputs A11 1,2,3 2 mΑ = VIL or VIH V_{DD} = +15 V 2 A11 1,2,3 V_{DD} | = +5 V All digital inputs 100 A11 1 = 0 V or VDD 2,3 500 All 1 100 | Y_{DD} |= +15 Y 2,3 500 |ppm/°C| Gain temperature ΔAE/Δt 4/ V_{CC} = +5 V A11 1,2,3 ±70 coefficient V_{CC} = +15 V A11 1,2,3 ±35 $V_{REF} = \pm 10 \text{ V},$ 100 kHz sinewave, Feedthrough error FTREFA | V_{CC} |= +5 V **LIA** 4,5,6 -70 dΒ V_{REFA} to OUTA DAC latches loaded | V_{DD} |= +15 V A11 4,5,6 -70 with 0000 0000 Feedthrough error IFTREFB V_{CC} = +5 V 4,5,6 -70 A11 V_{REFB} to OUTB | V_{DD} |= +15 V A11 4,5,6 -70 TA = +25°C Digital input capacitance V_{DP}5_V CIN All 4 10 pF DBO-DB7 V_{DD} = +15 V A11 4 20 V_{DD} = +5 V A11 4 10 WR,CS,DACA/DACB TA = +25 C 6/ | V_{DD} |= +15 V A11 4 15

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued. Conditions $\frac{1}{c}$ -55°C < T_A < +125°C unless otherwise specified Unit Limits Test Symbol Device |Group A subgroups types Min Max V_{DD} Output capacitance | COUTA 4 50 pF A11 DAC latches loaded pin 2 with 0000 0000 50 $T_A = +25^{\circ}C$ ν_{DD} = +15 ν 4 A11 V_{DD}_{5 V} Output capacitance 4 50 COUTB A11 pin 20 DAC latches loaded with 0000 0000 T_A = +25°C V_{DD}_{15 V} A11 4 50 V_{DD} 4 120 Output capacitance | COUTA A11 DAC latches loaded pin 2 with 1111 1111 T_A = +25°C 4 120 ν_{DD} = +15 ν **A11** Output capacitance | COUTB V_{DD} = +5 V A11 4 120 pin 20 V_{DD} - +15 V 4 120 A11 ν_{DD} +5 γ Chip select to 7/ 9 A11 200 tcs ns write setup time 10,11 230 V_{DD} = +15 V A11 9 60 10,11 80 Chip select to write hold time A11 9 20 ¥_{DD} = +5 γ 7/ tCH 10,11 30 V_{DD} = +15 γ 9 A11 10 15 10,11 V_{DD} = +5 V 9 180 Write pulse width A11 twR tCS > tWR, 10,11 200 9 | V_{DD} |= +15 V 60 A11 10,11 80 See footnotes at end of table. **STANDARDIZED** SIZE A 5962-87701 **MILITARY DRAWING** DEFENSE ELECTRONICS SUPPLY CENTER **REVISION LEVEL** SHEET DAYTON, OHIO 45444 8

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TABLE I. Electrical performance characteristics - Continued. Conditions $\frac{1}{C}$ -55°C < TA < +125°C unless otherwise specified Test Symbol 1 Device | Group A Limits Unit types Isubgroups Min Max 9 110 ns Data valid to A11 7/ Ψ_{DD} = +5 V tos write setup time 10,11 130 9 50 ν_{DD} = +15 ν **A11** 10,11 70 Data valid to <u>7/</u> V_{DD} = +5 V A11 9,10,11 10 t_{DH} write hold time V_{DD} = +15 V A11 9,10,11 10 V_{DD} - +5 v 9 200 Data select to A11 tas 7/ write setup time 10,11 230 V_{DD} = +15 V 9 60 A11 10,11 80 Data select to 20 7/ | V_{DD} |= +5 V A11 tAH write hold time 10,11 30 V_{DD} = +15 V 9 A11 10 15 10,11 % Reference input A11 1,2,3 ±1 RMIN 4/ | V_{DD} |= +5 V resistance match **AVREF** V_{DD} = +15 V **A11** ±1 1,2,3 $\frac{4}{\text{VREFA}} = \pm 10 \text{ V},$ 100 kHz sinewave, Channel-to-channel V_{DD} = +5 V 60 đΒ 1CH_{ISO} A11 4,5,6 isolation V_{REFA} to OUTB ν_{DD} = +15 ν A11 60 $V_{REFB} = 0 V$ 4,5,6 See footnotes at end of table. **STANDARDIZED** SIZE A 5962-87701

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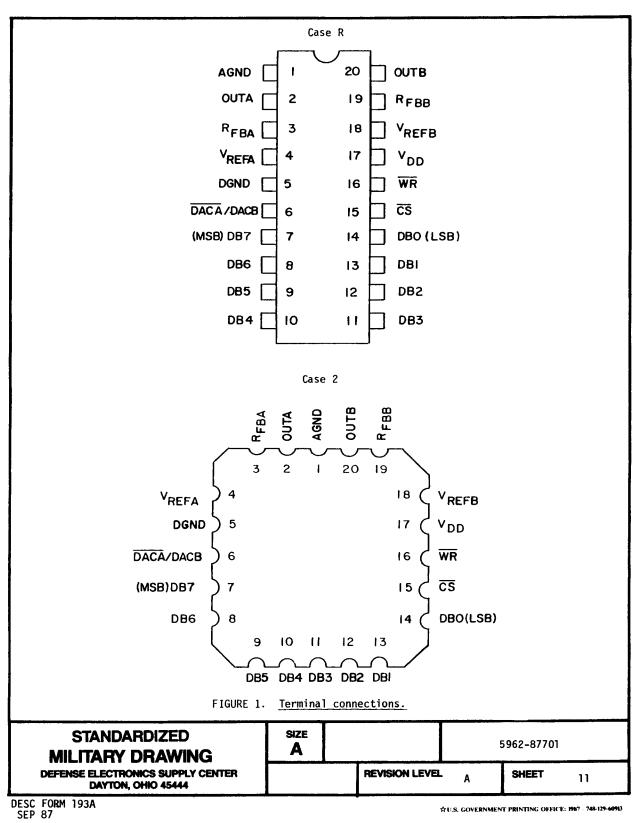
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Test	Symbol	Conditions -55°C < TA < +	Device	Group A	L1	Unit		
		-55°C < T _A < + unless otherwise s	types	subgroups	Min	Max	<u> </u>	
isolation	CH _{ISO}	4/ V _{REFB} = ±10 V,	V _{DD}	A11	4,5,6		60	dB
V _{REFB} to OUTA	 - 	100 kHz sinewave, VREFA = 0 V	 V _{DD} = +15 V	 A11 	4,5,6		60	
Output current settling time	t _{SL}	4/	 V _{DD} = +5 V	 A11 	9,10,11		350	ns
•			V _{DD} =	ATT	9,10,11		180	

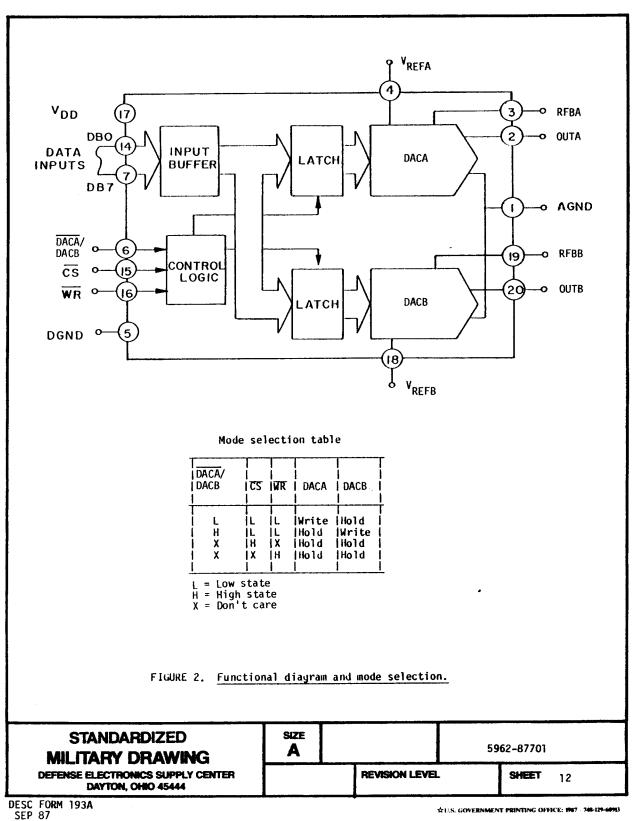
- $1/V_{OUT1} = 0$ V; $V_{REF} = +10$ V, AGND = DGND unless otherwise specified.
- 2/ See 4.3.1d.
- 3/ Measured using internal RFBA and RFBB. Gain error is adjustable.
- 4/ Guaranteed if not tested.
- 5/ Feedthrough error can be reduced by connecting the metal 11d to ground.
- 6/ See 4.3.1c.
- 7/ Timing in accordance with figure 3.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

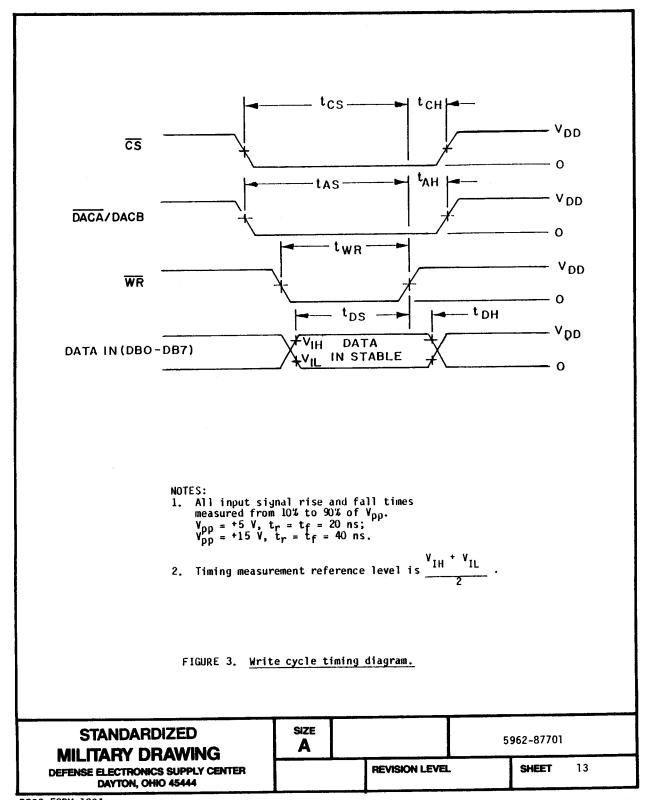
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- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
 - c. Optional subgroup 12 is used for grading and part selection at +25°C, it is not included in PDA.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 ($C_{\hbox{\scriptsize IN}}$ measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.
 - d. Optional subgroup 12 is used for grading and part selection at +25°C.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

 MIL-STD-883 test requirements 	Subgroups Subgroups (per method 5005, table I)
 Interim electrical parameters (method 5004)	1 1
 Final electrical test parameters (method 5004)	1*,2,3,12
 Group A test requirements (method 5005)	 1,2,3,4,5,6,9,
 Groups C and D end-point electrical parameters (method 5005)	1

* PDA applies to subgroup 1.
 ** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 <u>Approved sources of supply</u>. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number 	Vendor CAGE number	Vendor similar part number <u>1</u> /
5962-8770101RX /	24355 54186 06665	AD7528SQ/883B MP7528SD/883 PM7528BR/883B
5962-87701012X	24355 54186 06665	 AD7528SE/883B MP7528SL/883 PM7528BRC/883B
5962-8770102RX /	24355 54186 06665	AD7528TQ/883B MP7528TD/883 PM7528BR/883B
5962-87701022X /	24355 54186 06665	AD7528TE/883B MP7528TL/883 PM7528BRC/883B
 5962-8770103RX / 	24355 54186 06665	AD7528UQ/883B MP7528UD/883 PM7528AR/883B
 5962-87701032X	24355 54186 06665	AD7528UE/883B MP7528UL/883 PM7528ARC/883B

 $\frac{1}{\text{Items}} \begin{tabular}{ll} \hline \textbf{Caution.} & \textbf{Do not use this number for item acquisition.} \\ \hline \textbf{Items} & \textbf{acquired to this number may not satisfy the performance requirements of this drawing.} \\ \hline \end{tabular}$

Vendor CAGE number	Vendor name and address
06665	Precision Monolithics Incorporated 1500 Space Park Drive Santa Clara, CA 95050
24355	Analog Devices 1 Technology Way Norwood, MA 02062
54186	Micro Power Systems 3100 Alfred Street Santa Clara, CA 95054

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